



**Product / Package Information**

Package	LGA
Body Size (mm)	3 X 3
Ball Count	16
Terminal Finish	Gold

**Environmental Information**

RoHS Compliant	Yes - with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silica	60676-86-0	1.23 E-02	86.20	862000	50.74		507417
Thermosets	Epoxy resin	Proprietary	8.58 E-04	6.00	60000	3.53		35319
Thermosets	Phenol Resin	Proprietary	8.58 E-04	6.00	60000	3.53		35319
Other inorganic materials	Metal Hydroxide	Proprietary	2.15 E-04	1.50	15000	0.88		8830
Other inorganic materials	Carbon Black	1333-86-4	4.29 E-05	0.30	3000	0.18		1766
Subtotal	Subtotal		1.43 E-02	100.0	1000000	58.87		588651

**Laminate**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Glass	Continuous filament Fiber Glass	65997-17-3						
Copper & its alloys	Copper	Proprietary						
Thermoset	Bismaleimide/Triazine	13676-54-5						
Thermoset	Epoxy Resin	Proprietary						
Other inorganic materials	Inorganic Filler	Proprietary						
	Laminate Core Subtotal		1.90 E-03	38.80	387755	7.82		78212
Other organic materials	Diethylene Glycol Ethyl Ether Acetate	112-15-2						
Other organic materials	Dipropylene Glycol Methyl Ether	34590-94-8						
Other organic materials	Heavy Aromatic Naphtha (petroleum)	64742-94-5						
	Soldermask Subtotal		9.00 E-04	18.4	183673	3.70		37048
Copper & its alloys	Copper	7440-50-8	1.10 E-03	22.4	224490	4.53		45281
Nickel & its alloys	Nickel	7440-02-0	9.00 E-04	18.4	183673	3.70		37048
Precious metals	Gold	7440-57-5	1.00 E-04	2.00	20408	0.41		4116
Subtotal	Subtotal		4.90 E-03	100.0	1000000	20		201706

**Seal Glass**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Glass	Lead borosilicate glass	Proprietary	7.74 E-04	87.50	875000	3.19		31859
Glass	Aluminosilicate glass	Proprietary	1.11 E-04	12.50	125000	0.46		4551
Subtotal	Subtotal		8.85 E-04	100	1000000	3.64		36411

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Precious metals	Gold	7440-57-5	6.43 E-05	99	990000	0.26		2648
Precious metals	Palladium	7440-05-3	6.50 E-07	1	10000	0.00		27
Subtotal	Subtotal		6.50 E-05	100	1000000	0.27		2674

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Doped Silicon	7440-21-3	2.24 E-03	100	1000000	9.23		92346

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level		
				Percentage (%)	PPM	Percentage (%)	PPM	
Other inorganic materials	Silicon dioxide	Proprietary	7.95 E-04	41.86	418600	3.27		32740
Other organic materials	Diester resin	Proprietary	4.86 E-04	25.58	255800	2.00		20007
Other organic materials	Functionalized ester	Proprietary	3.53 E-04	18.60	186000	1.45		14548
Thermoset	Epoxy resin	Proprietary	1.33 E-04	6.98	69800	0.55		5459
Other organic materials	Polymeric material	Proprietary	1.33 E-04	6.98	69800	0.55		5459
Subtotal	Subtotal		1.90 E-03	100.00	1000000	7.82		78212

<b>Package Totals</b>			<b>Weight (g)</b>	<b>2.43 E-02</b>		<b>Percentage (%)</b>	<b>100.00</b>	<b>PPM</b>	<b>1000000</b>
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Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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